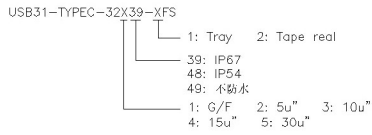


Pin	Signal Name	Mating Sequence	Pin	Signal Name	Mating Sequence
A1	GND	First	B12	GND	First
A2	SSTXp1	Second	B11	SSRXp1	Second
A3	SSTXn1	Second	B10	SSRXn1	Second
A4	Vbus	First	B9	Vbus	First
A5	CC1	Second	B8	SBU2	Second
A6	Dp1	Second	B7	Dn2	Second
A7	Dn1	Second	B6	Dp2	Second
A8	SBU1	Second	B5	CC2	Second
A9	Vbus	First	B4	Vbus	First
A10	SSRXn2	Second	B3	SSTXn2	Second
A11	SSRXp2	Second	B2	SSTXp2	Second
A12	GND	First	B1	GND	First
SHELL	GND		SHELL	GND	

Material
 Housing Material: High temperature thermoplastic
 Contact Terminal: High Grade Copper Alloy
 Metallic Shell: Stainless Steel
 Cover Shell: Iron
 Inner Ground Cover Shell: Stainless Steel
 Mid Plate: Stainless Steel
 Plating
 Data Contact
 Underplating: 50µ" Min. Nickel
 Contact Plating: 1µ" Gold
 Solder Area: 80µ" Matte Tin
 Shell
 Metallic Shell: 50µ" Min. Nickel
 Cover Shell
 Metallic Shell: 80µ" Min. Nickel
 Inner Ground Cover Shell
 Metallic Shell: 50µ" Min. Nickel
 Electrical
 Voltage Rating: 20V DC
 Current Rating: Vbus pins collectively 5.00A, GND pins collectively 6.25A, B5 pin 1.25A, Other pins 0.25A per pin.
 Contact Resistance: 40mΩ Max.
 Insulation resistance: 100 MΩ MIN.
 Dielectric withstanding voltage: 100V AC/Minute
 Mechanical
 Durability: 10,000 cycles
 Mating Force: 5 to 20N
 Unmating Force: 8 to 20N (post test)



MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DATE	SCALE: N/A	MODEL TYPE: USB 3.1 TYPE
△ X					ANGULAR ±5°			
△ X					L ≤ 4 ±0.2		VIEW:	PART NO.:
△ X					4 < L ≤ 16 ±0.3		UNIT: mm	DWG NO.:
					16 < L ≤ 63 ±0.4		SIZE: A4	USB31-TYPEC-32X39-XFS
					L > 63 ±0.5			WEIGHT 1.0g
								SHEET 1/1
								REVISION A0